

## 74LCX2244

### Low Voltage Buffer/Line Driver with 5V Tolerant Inputs and Outputs with 26Ω Series Resistors in the Outputs

#### General Description

The LCX2244 contains eight non-inverting buffers with 3-STATE outputs. The device may be employed as a memory address driver, clock driver and bus-oriented transmitter/receiver. The LCX2244 is designed for low voltage (2.5V or 3.3V)  $V_{CC}$  applications with capability of interfacing to a 5V signal environment. The 26Ω-series resistors help reduce output overshoot and undershoot.

The LCX2244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

#### Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V  $V_{CC}$  specifications provided
- 7.5 ns  $t_{PD}$  max ( $V_{CC} = 3.3V$ ) 10  $\mu A$   $I_{CC}$  max
- Power down high impedance inputs and outputs
- 26Ω-series resistors in the outputs
- Supports live insertion/withdrawal (Note 1)
- $\pm 12$  mA output drive ( $V_{CC} = 3.0V$ )
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

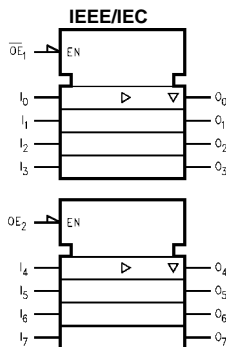
**Note 1:** To ensure the high-impedance state during power up or down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pull-up resistor; the minimum value or the resistor is determined by the current-sourcing capability of the driver.

#### Ordering Code:

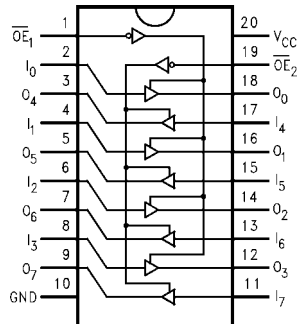
Order Number	Package Number	Package Description
74LCX2244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX2244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX2244MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LCX2244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

#### Logic Symbol



#### Connection Diagram



## Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
$I_0-I_7$	Inputs
$O_0-O_7$	Outputs

## Truth Tables

Inputs		Outputs
$\overline{OE}_1$	$I_n$	(Pins 12, 14, 16, 18)
L	L	L
L	H	H
H	X	Z

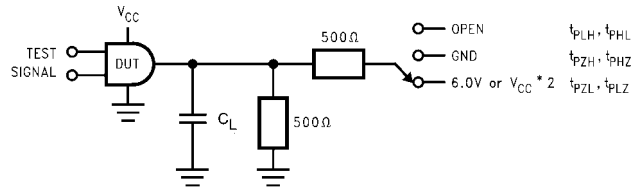
Inputs		Outputs
$\overline{OE}_2$	$I_n$	(Pins 3, 5, 7, 9)
L	H	L
L	H	H
H	X	Z

H = HIGH Voltage Level  
 X = Immaterial  
 L = LOW Voltage Level  
 Z = High Impedance

Absolute Maximum Ratings (Note 2)						
Symbol	Parameter	Value	Conditions	Units		
V <sub>CC</sub>	Supply Voltage	-0.5 to +7.0		V		
V <sub>I</sub>	DC Input Voltage	-0.5 to +7.0		V		
V <sub>O</sub>	DC Output Voltage	-0.5 to +7.0 -0.5 to V <sub>CC</sub> + 0.5	Output in 3-STATE Output in HIGH or LOW State (Note 3)	V		
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA		
I <sub>OK</sub>	DC Output Diode Current	-50 +50	V <sub>O</sub> < GND V <sub>O</sub> > V <sub>CC</sub>	mA		
I <sub>O</sub>	DC Output Source/Sink Current	±50		mA		
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100		mA		
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100		mA		
T <sub>STG</sub>	Storage Temperature	-65 to +150		°C		
Recommended Operating Conditions (Note 4)						
Symbol	Parameter	Min	Max	Units		
V <sub>CC</sub>	Supply Voltage	Operating	2.0	3.6	V	
		Data Retention	1.5	3.6		
V <sub>I</sub>	Input Voltage	0	5.5	V		
V <sub>O</sub>	Output Voltage	HIGH or LOW State	0	V <sub>CC</sub>	V	
		3-STATE	0	5.5		
I <sub>OH</sub> /I <sub>OL</sub>	Output Current	V <sub>CC</sub> = 3.0V – 3.6V		±12	mA	
		V <sub>CC</sub> = 2.7V – 3.0V		±8		
		V <sub>CC</sub> = 2.3V – 2.7V		±4		
T <sub>A</sub>	Free-Air Operating Temperature	-40	85	°C		
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V – 2.0V, V <sub>CC</sub> = 3.0V	0	10	ns/V		
<p><b>Note 2:</b> The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.</p> <p><b>Note 3:</b> I<sub>O</sub> Absolute Maximum Rating must be observed.</p> <p><b>Note 4:</b> Unused inputs must be held HIGH or LOW. They may not float.</p>						
DC Electrical Characteristics						
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = -40°C to +85°C		Units
				Min	Max	
V <sub>IH</sub>	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		
V <sub>IL</sub>	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 – 3.6		0.8	
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100 μA	2.3 – 3.6	V <sub>CC</sub> - 0.2		V
			2.3	1.8		
			2.7	2.2		
			3.0	2.4		
			2.7	2.0		
			3.0	2.0		
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 – 3.6		0.2	V
			2.3		0.6	
			2.7		0.4	
			3.0		0.55	
			2.7		0.6	
			3.0		0.8	
I <sub>I</sub>	Input Leakage Current	0 ≤ V <sub>I</sub> ≤ 5.5V	2.3 – 3.6		±5.0	μA
I <sub>OZ</sub>	3-STATE Output Leakage	0 ≤ V <sub>O</sub> ≤ 5.5V V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	2.3 – 3.6		±5.0	μA

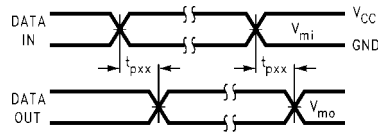
DC Electrical Characteristics (Continued)								
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = -40°C to +85°C		Units		
				Min	Max			
I <sub>OFF</sub>	Power-Off Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 5.5V	0		10	μA		
I <sub>CC</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3 – 3.6		10	μA		
		3.6V ≤ V <sub>I</sub> , V <sub>O</sub> ≤ 5.5V (Note 5)	2.3 – 3.6		±10			
ΔI <sub>CC</sub>	Increase in I <sub>CC</sub> per Input	V <sub>IH</sub> = V <sub>CC</sub> - 0.6V	2.3 – 3.6		500	μA		
<b>Note 5:</b> Outputs disabled or 3-STATE only.								
AC Electrical Characteristics								
Symbol	Parameter	T <sub>A</sub> = -40°C to +85°C, R <sub>L</sub> = 500Ω						Units
		V <sub>CC</sub> = 3.3V ± 0.3V		V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 2.5 ± 0.2V		
		C <sub>L</sub> = 50pF		C <sub>L</sub> = 50pF		C <sub>L</sub> = 30pF		
		Min	Max	Min	Max	Min	Max	
t <sub>PHL</sub>	Propagation Delay	1.5	7.5	1.5	8.5	1.5	9.0	ns
t <sub>PLH</sub>	Data to Output	1.5	7.5	1.5	8.5	1.5	9.0	
t <sub>PZL</sub>	Output Enable Time	1.5	9.0	1.5	10.0	1.5	10.5	ns
t <sub>PZH</sub>		1.5	9.0	1.5	10.0	1.5	10.5	
t <sub>PLZ</sub>	Output Disable Time	1.5	7.0	1.5	8.0	1.5	8.4	ns
t <sub>PHZ</sub>		1.5	7.0	1.5	8.0	1.5	8.4	
t <sub>OSSL</sub>	Output to Output Skew (Note 6)		1.0					ns
t <sub>OSLH</sub>			1.0					
<b>Note 6:</b> Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t <sub>OSSL</sub> ) or LOW-to-HIGH (t <sub>OSLH</sub> ).								
Dynamic Switching Characteristics								
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C		Units		
				Typical				
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V	3.3	0.35		V		
			2.5	0.25				
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V	3.3	-0.35		V		
			2.5	-0.25				
Capacitance								
Symbol	Parameter	Conditions	Typical		Units			
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = Open, V <sub>I</sub> = 0V or V <sub>CC</sub>	7		pF			
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CC</sub>	8		pF			
C <sub>PD</sub>	Power Dissipation Capacitance	V <sub>CC</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CC</sub> , f = 10 MHz	25		pF			

**AC LOADING and WAVEFORMS** Generic for LCX Family

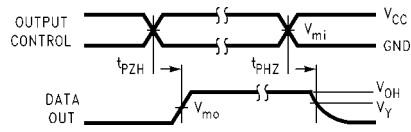


**FIGURE 1. AC Test Circuit ( $C_L$  includes probe and jig capacitance)**

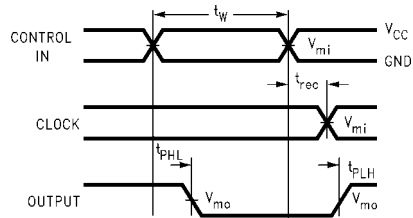
Test	Switch
$t_{PLH}, t_{PHL}$	Open
$t_{PZL}, t_{PLZ}$	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
$t_{PZH}, t_{PHZ}$	GND



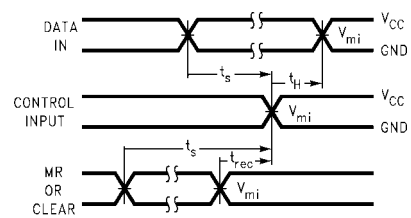
**Waveform for Inverting and Non-Inverting Functions**



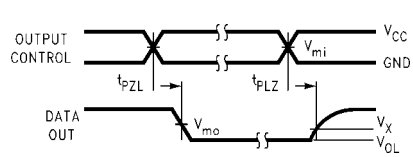
**3-STATE Output High Enable and Disable Times for Logic**



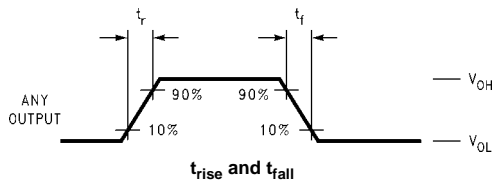
**Propagation Delay, Pulse Width and  $t_{rec}$  Waveforms**



**Setup Time, Hold Time and Recovery Time for Logic**



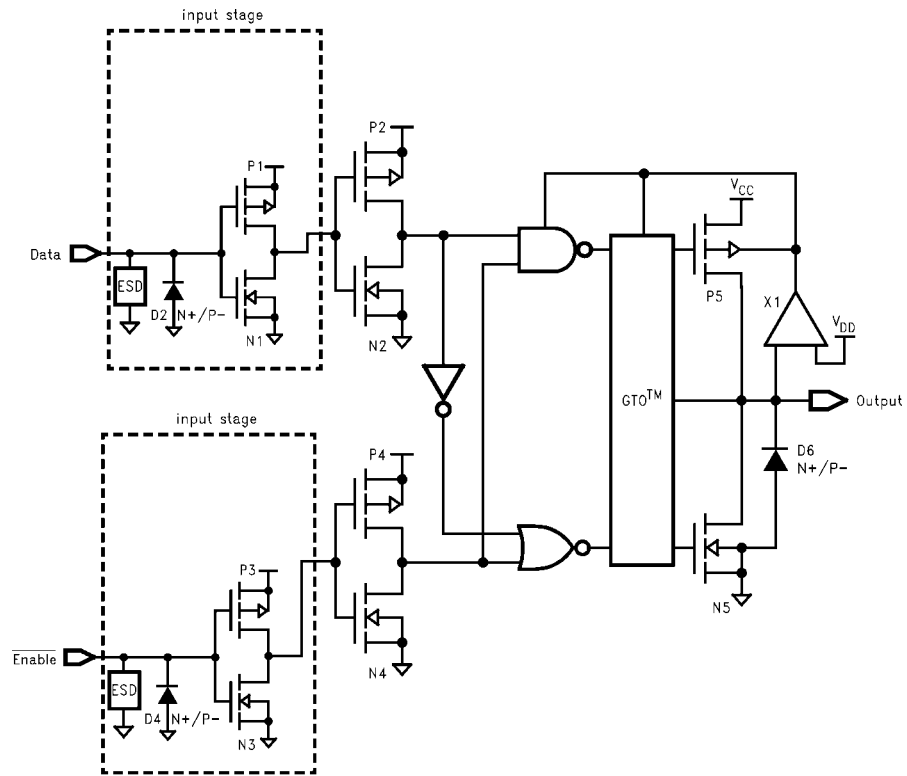
**3-STATE Output Low Enable and Disable Times for Logic**



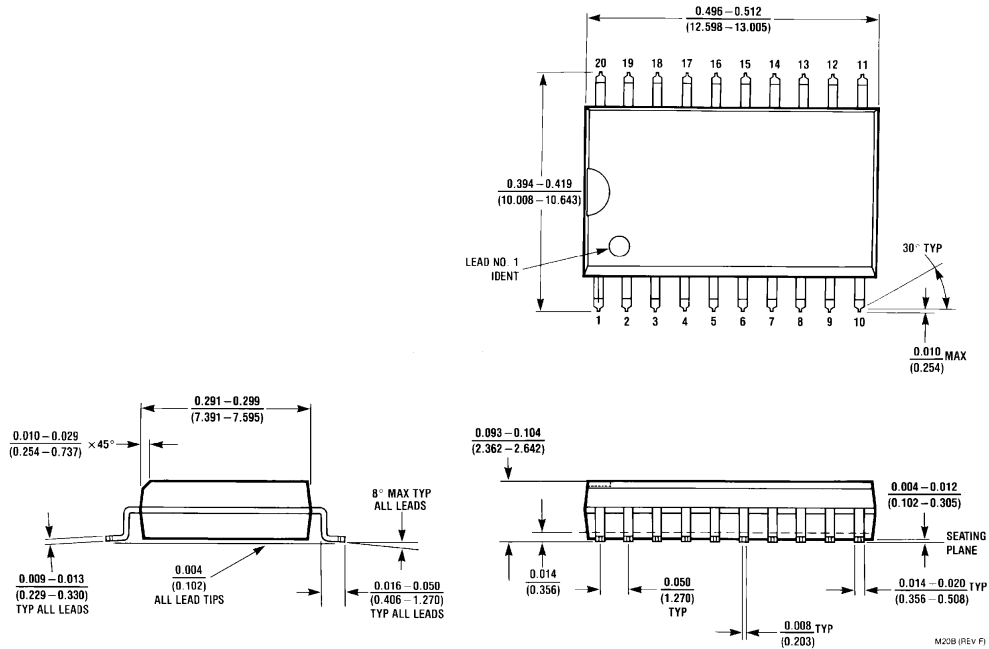
**FIGURE 2. Waveforms**  
(Input Characteristics;  $f = 1MHz, t_R = t_F = 3ns$ )

Symbol	$V_{CC}$		
	$3.3V \pm 0.3V$	2.7V	$2.5V \pm 0.2V$
$V_{mi}$	1.5V	1.5V	$V_{CC}/2$
$V_{mo}$	1.5V	1.5V	$V_{CC}/2$
$V_x$	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
$V_y$	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

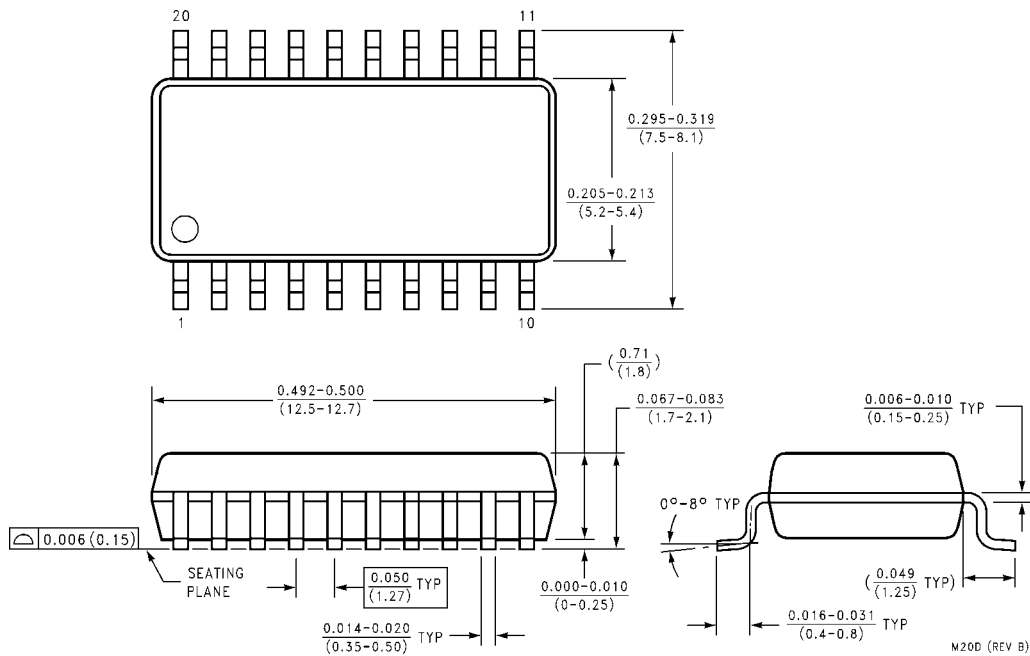
**Schematic Diagram** Generic for LCX Family



**Physical Dimensions** inches (millimeters) unless otherwise noted

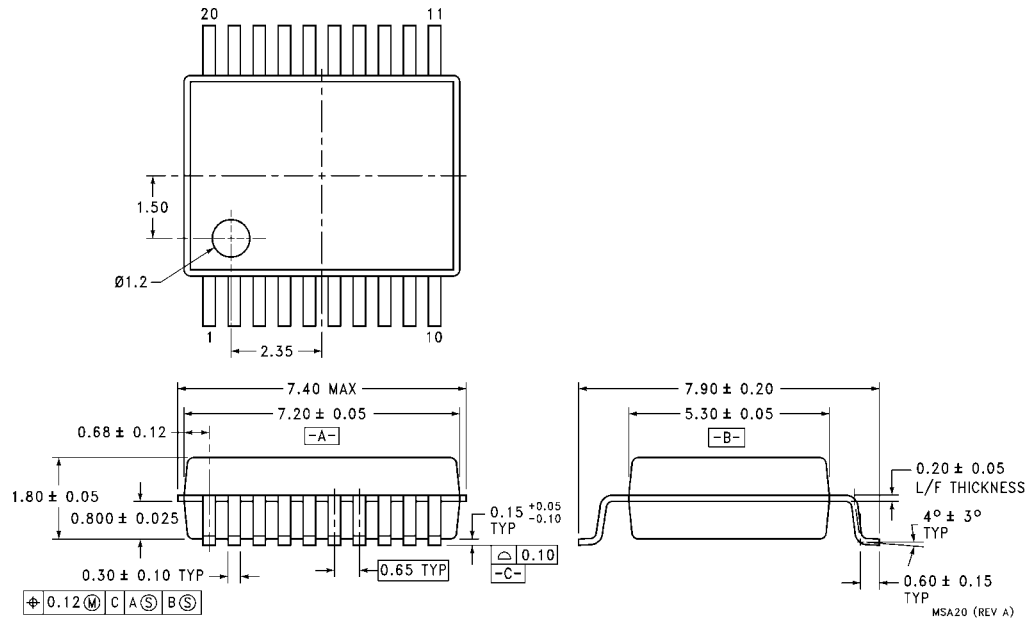


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide  
Package Number M20B**



**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

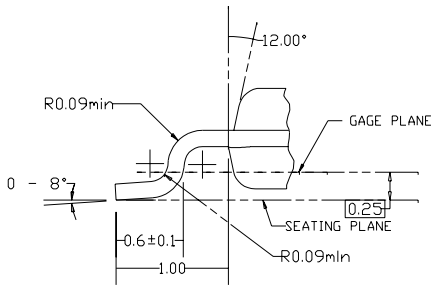
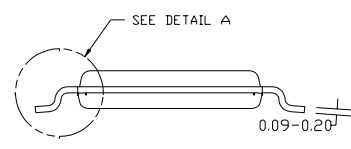
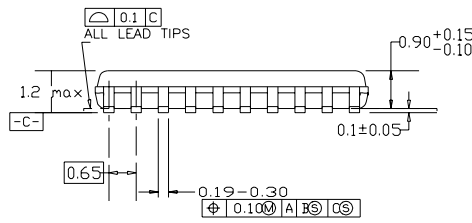
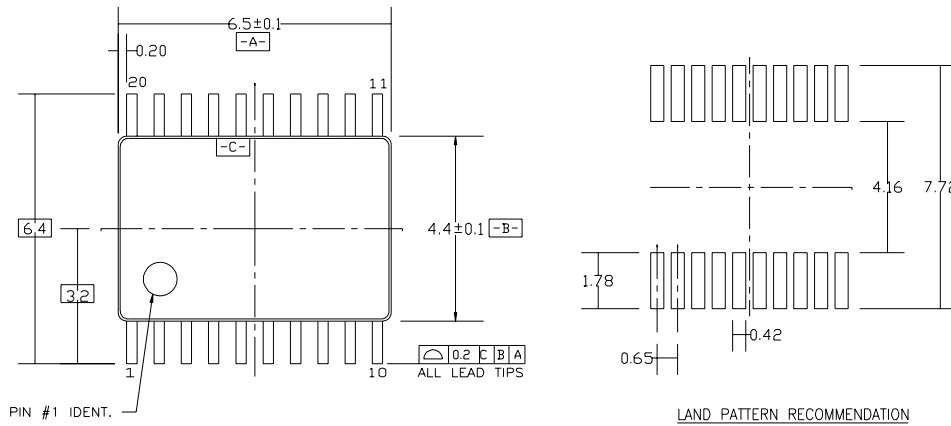


**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide  
Package Number MSA20**

MSA20 (REV A)



**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 43.4mm Wide Package Number MTC20**

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